

<b>Notice of References Cited</b>		Application/Control No.	Applicant(s)/Patent Under Reexamination STEINMANN ET AL.	
		Examiner Nghia M. Doan	Art Unit 2825	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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	C	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Lane et al., The Design of Thin-Film Polysilicon Resistors for Analog IC applications, April, 1989, IEEE Transactions on Electron Devices, Vol. 36, No. 4, Pages 738-744
	V	Richard et al., Thermal Properties of Very Fast Transistors, August, 1970, IEEE Transactions on Electron Devices, Vol. 17, No. 8, Pages 586-594
	W	Chung et al., Junction-to-Top and Junction-to-Board Thermal Resistance- Measurement for 119 BGA Packages, May, 1999, Fifteenth IEEE SEMI-THERM Symposium, Page142-150
	X	Pence et al., Package Thermal Resistance: Geometric Effect in Convention and Hybird Packages, June, 1990, IEEE Transactions on Components, Hybrids, and Manufacturing Technology, Vol. 13, No. 2 page 586-594

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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